


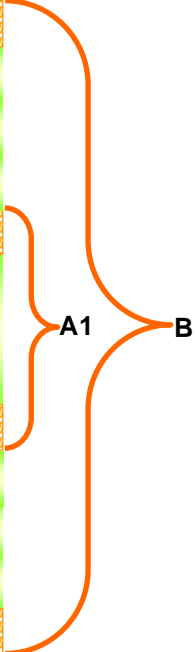







**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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**04 157 FR4 35 L51.35 P18\_10**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**04\_157\_FR4\_35\_L51.35\_p18\_10**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	35 $\mu$	Copper		
	100 $\mu$	Prepreg	(100 $\mu$ PrePreg-Type: 2125)	
	180 $\mu$	Prepreg	(180 $\mu$ PrePreg-Type: 7628)	
	180 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	510 $\mu$	L-FR4		
<b>Layer-3</b>	35 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	100 $\mu$	Prepreg		
<b>Layer-99</b>	35 $\mu$	Copper		

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